



# Product Change Notification



Product Group: OPT/Fri Dec 17, 2021/PCN-OPT-1191-2021-REV-0

## TSMF1000, TSMF1020, TSMF1030 - Change in Chip

**DESCRIPTION OF CHANGE:** A new chip generation will be introduced in TSMF1000, TSMF1020, TSMF1030 dome lens products.

With the new chip, the devices will have more than 5 times increased radiant intensity and narrow emission angle. The high performance chip allows customers to achieve the required intensity with lower driving current.

**REASON FOR CHANGE:** Introduction of new chip generation with improved electro-optical performance.

**EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE:** No influence on quality and reliability expected. Nevertheless, we recommend to test the product in customers application.

**PART NUMBERS/SERIES/FAMILIES AFFECTED:** TSMF1000, TSMF1000-GS15, TSMF1020, TSMF1020-GS15, TSMF1030

**VISHAY BRAND(s):** Vishay Semiconductors

### TIME SCHEDULE:

Start Shipment Date: Sun May 1, 2022

**SAMPLE AVAILABILITY:** 31. Jan.2022

**PRODUCT IDENTIFICATION:** Date code

**QUALIFICATION DATA:** Available upon request

**This PCN is considered approved, without further notification, unless we receive specific customer concerns before Fri Apr 15, 2022 or as specified by contract.**

**ISSUED BY:** Mohankumar Kannusamy, mohankumar.kannusamy@vishay.com

**For further information, please contact your regional Vishay office.**

### CONTACT INFORMATION:

#### Americas

VISHAY Intertechnologies, Inc.  
2585 Junction Avenue  
SanJose California United States 95134  
Phone: 1-408-567-8358  
Fax: +1 408-240-5687

#### Europe

VISHAY Semiconductor GmbH  
Theresienstr. 2  
Heilbronn Germany 74072  
Phone: +49-7131-7498-645  
Fax: +49-7131-67-3144

#### Asia

+1 408-240-5687  
25 Tampines Street 92  
Singapore Singapore 528877  
Phone: +65 6780 7879  
Fax: +65 6780 7897

Vishay Intertechnology, Inc.

Corporate Headquarters 63 Lincoln Highway, Malvern, PA 19355-2143 U.S.A. Phone (610) 644-1300 Fax (610) 296-0657 [www.vishay.com](http://www.vishay.com)

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# TSMF1000, TSMF1020, TSMF1030 - Change in Chip

Change overview

PCN: OPT-1191-2021 Rev. 0

# Change Overview

Before PCN

BASIC CHARACTERISTICS (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 20 mA	V <sub>F</sub>		1.3	1.5	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>		2.4		V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>V<sub>F</sub></sub>		- 1.8		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	C <sub>j</sub>		160		pF
Radiant intensity	I <sub>F</sub> = 20 mA	I <sub>e</sub>	2.5	5	13	mW/sr
	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 100 μs	I <sub>e</sub>		25		mW/sr
Radiant power	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>		35		mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 20 mA	TKφ <sub>e</sub>		- 0.6		%/K
Angle of half intensity		φ		± 17		deg
Peak wavelength	I <sub>F</sub> = 20 mA	λ <sub>p</sub>		890		nm
Spectral bandwidth	I <sub>F</sub> = 20 mA	Δλ		40		nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 20 mA	TKλ <sub>p</sub>		0.2		nm/K
Rise time	I <sub>F</sub> = 20 mA	t <sub>r</sub>		30		ns
Fall time	I <sub>F</sub> = 20 mA	t <sub>f</sub>		30		ns
Cut-off frequency	I <sub>DC</sub> = 70 mA, I <sub>AC</sub> = 30 mA pp	f <sub>c</sub>		12		MHz
Virtual source diameter		d		1.2		mm

After PCN

BASIC CHARACTERISTICS (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I <sub>F</sub> = 20 mA	V <sub>F</sub>	-	1.3	1.5	V
	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 100 μs	V <sub>F</sub>	-	1.5	-	V
	I <sub>F</sub> = 1 A, t <sub>p</sub> = 100 μs	V <sub>F</sub>	-	2.6	-	V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 20 mA	TK <sub>V<sub>F</sub></sub>	-	-1.4	-	mV/K
Reverse current		I <sub>R</sub>	Not designed for reverse operation			μA
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	C <sub>j</sub>	-	56	-	pF
Radiant intensity	I <sub>F</sub> = 20 mA	I <sub>e</sub>	15	27	40	mW/sr
	I <sub>F</sub> = 100 mA, t <sub>p</sub> = 100 μs	I <sub>e</sub>	-	155	-	mW/sr
Radiant power	I <sub>F</sub> = 20 mA, t <sub>p</sub> = 20 ms	φ <sub>e</sub>	-	10	-	mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 20 mA	TKφ <sub>e</sub>	-	-0.3	-	%/K
Angle of half intensity		φ	-	± 11	-	°
Peak wavelength	I <sub>F</sub> = 20 mA	λ <sub>p</sub>	-	890	-	nm
Spectral bandwidth	I <sub>F</sub> = 20 mA	Δλ	-	35	-	nm
Temperature coefficient of λ <sub>p</sub>	I <sub>F</sub> = 20 mA	TKλ <sub>p</sub>	-	0.3	-	nm/K
Rise time	I <sub>F</sub> = 20 mA	t <sub>r</sub>	-	15	-	ns
Fall time	I <sub>F</sub> = 20 mA	t <sub>f</sub>	-	15	-	ns

Main changes:

- Higher radiant intensity (Typical : 5mw/sr to 27mw/sr)
- Emission angle/angle of half intensity has been reduced from +17° to +11°

# Before PCN

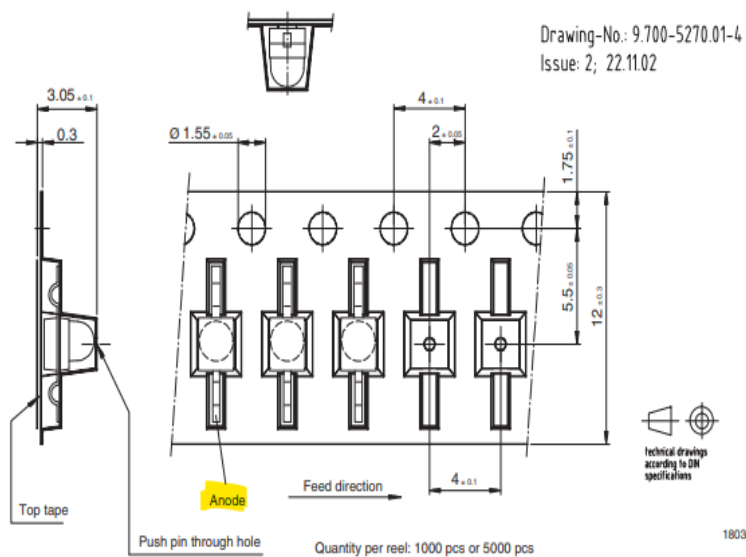


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TSMF1000, TSMF1020, TSMF1030

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TAPING DIMENSIONS in millimeters: TSMF1030



- **Changed device orientation**

# After PCN



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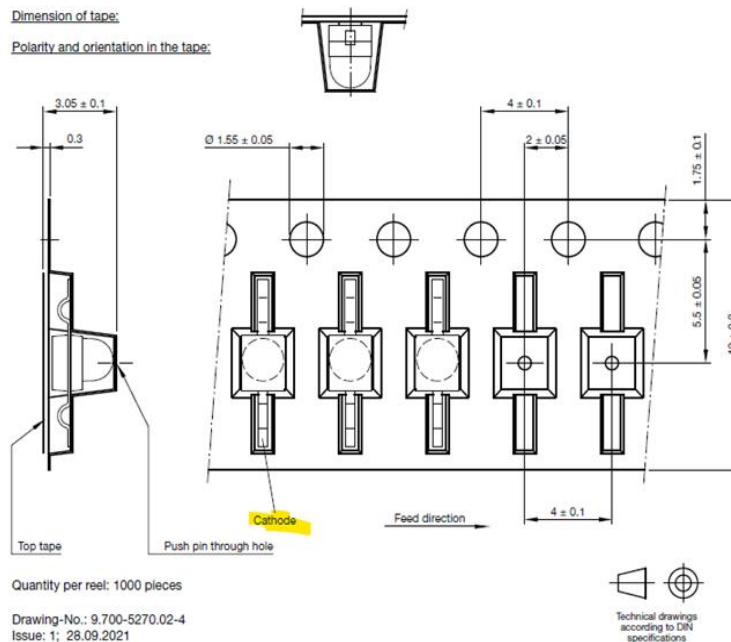
TSMF1000, TSMF1020, TSMF1030

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TAPING DIMENSIONS in millimeters: TSMF1030

Dimension of tape:

Polarity and orientation in the tape:





Thank you